



SOT1131-1

plastic, heatsink small outline package; 44 leads; low stand-off height, 0.65 mm pitch, 15.9 mm x 11.0 mm x 3.3 mm body

21 August 2018

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	HSOP44
Package type industry code	HSOP44
Package style descriptive code	HSOP (heatsink small outline package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	18-08-2010
Manufacturer package code	SOT1131

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	15.8	15.9	16	mm
package width	10.9	11	11.1	mm
seated height	-	-	3.5	mm
package height	3.2	3.3	3.5	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	44	-	



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2 Package outline

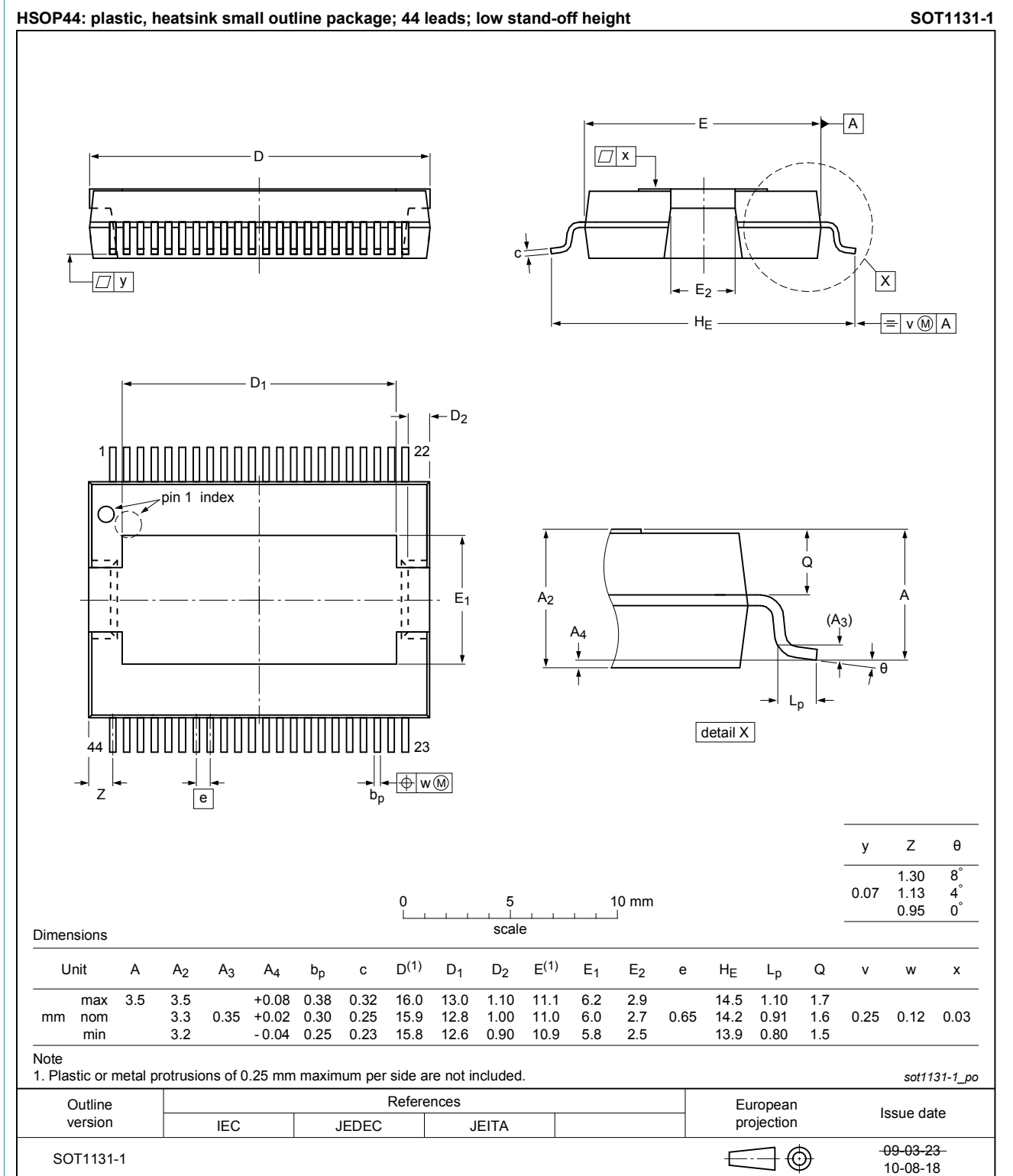


Figure 1. Package outline HSOP44 (SOT1131-1)

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3 Soldering

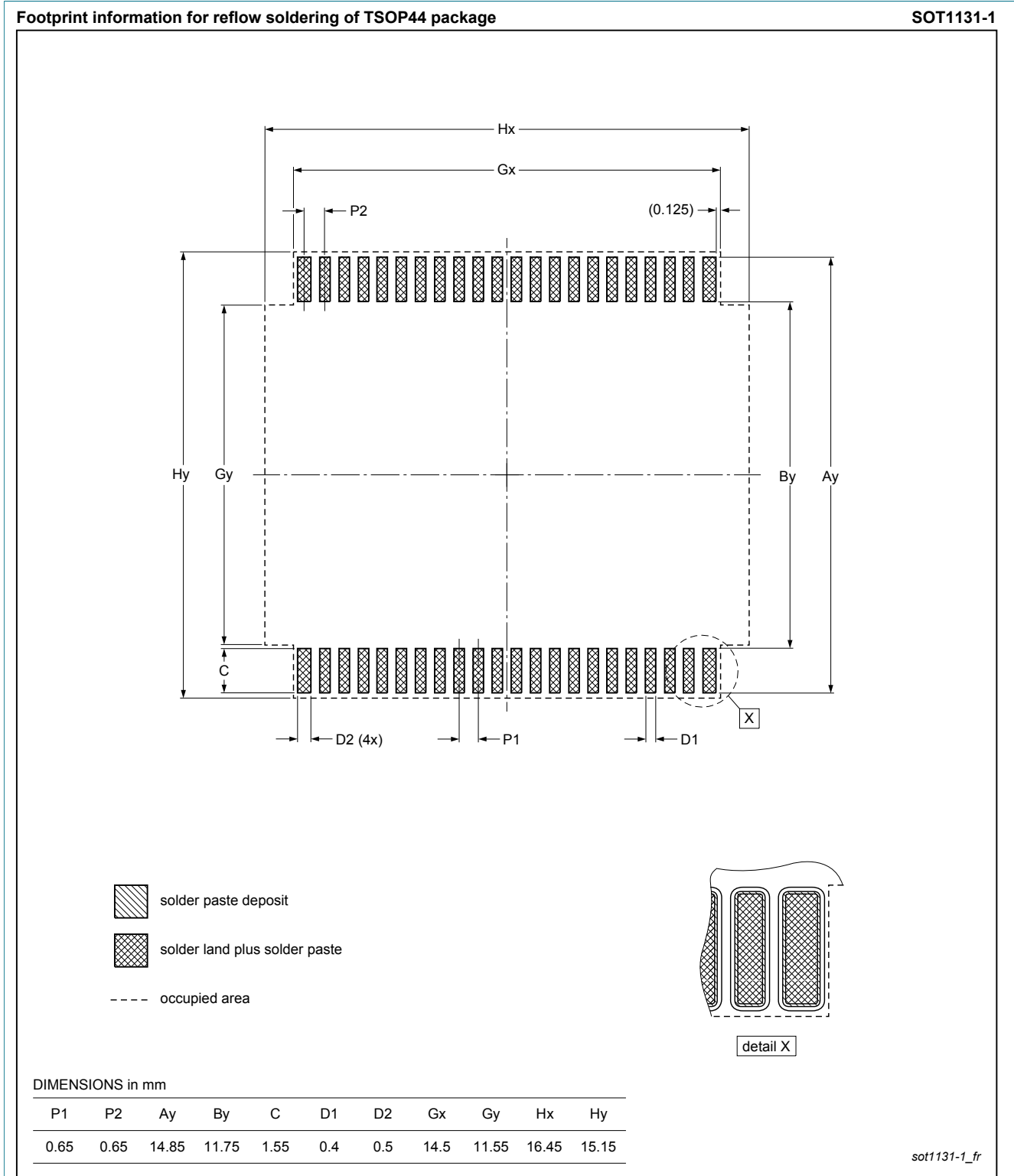


Figure 2. Reflow soldering footprint for HSOP44 (SOT1131-1)

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4 Legal information

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